Am2965/Am2966

Octal Dynamic Memory Drivers with Three-State Outputs

DISTINCTIVE CHARACTERISTICS

- Controlled rise and fall characteristics Internal resistors provide symmetrical drive to HIGH and LOW states, eliminating need for external series resistor.
- Output swings designed to drive 16K and 64K RAMs
 - V_{OH} guaranteed at V_{CC} -1.15V. Undershoot going LOW guaranteed at less than 0.5V.
- Large capacitive drive capability
 35mA min source or sink current at 2.0V. Propagation delays specified for 50pF and 500pF loads.
- Pin-compatible with 'S240 and 'S244
 Non-inverting Am2966 replaces 74S244; inverting Am2965 replaces 74S240. Faster than 'S240/244 under equivalent load.
- No-glitch outputs
 Outputs forced into OFF state during power up and down. No glitch coming out of three-state.

GENERAL DESCRIPTION

The Am2965 and Am2966 are designed and specified to drive the capacitive input characteristics of the address and control lines of MOS dynamic RAMs. The unique design of the lower output driver includes a collector resistor to control undershoot on the HIGH-to-LOW transition. The upper output driver pulls up to $V_{\rm CC}$ – 1.15V to be compatible with MOS memory and is designed to have a rise time symmetrical with the lower output's controlled fall time. This allows optimization of Dynamic RAM performance.

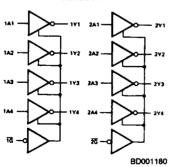
The Am2965 and Am2966 are pin-compatible with the popular 'S240 and 'S244 with identical 3-state output enable controls. The Am2965 has inverting drivers and the Am2966 has non-inverting drivers.

The inclusion of an internal resistor in the lower output driver eliminates the requirement for an external series resistor, therefore reducing package count and the board area required. The internal resistor controls the output fall and undershoot without slowing the output rise.

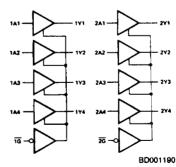
These devices are designed for use with the Am2964 Dynamic Memory Controller where large dynamic memories with highly capacitive input lines require additional buffering. Driving eight address lines or four RAS and four CAS lines with drivers on the same silicon chip also provides a significant performance advantage by minimizing skew between drivers. Each device has specified skew between drivers to improve the memory access worst case timing over the min and max tpD difference of unspecified devices.

BLOCK DIAGRAM

Am2965



Am2966



CONNECTION DIAGRAM Top View



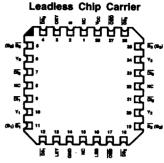
Note: Pin 1 is marked for orientation

Am2965

Inputa		Outputs
G A		Υ
Н	Х	Z
L	Н	L
LLL		H

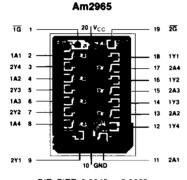
Am2966

Inputs		Outputs
Ğ	A	Y
Н	Х	Z
L	L	L
L	Н	- Н

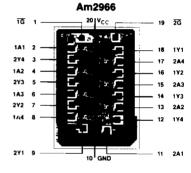


CD004870

METALLIZATION AND PAD LAYOUT



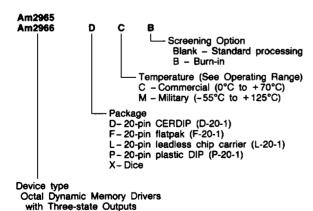
DIE SIZE 0.094" x 0.060"



DIE SIZE 0.094" x 0.066"

ORDERING INFORMATION

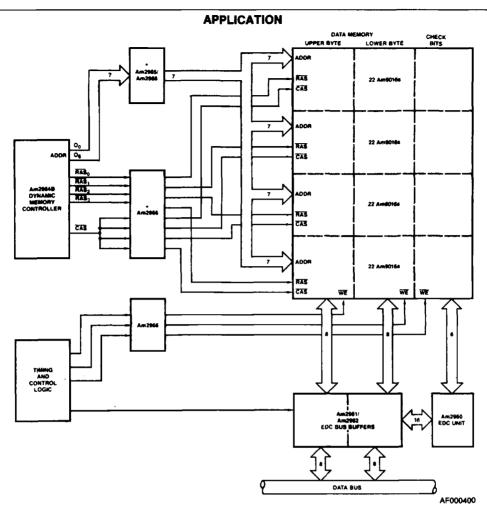
AMD products are available in several packages and operating ranges. The order number is formed by a combination of the following: Device number, speed option (if applicable), package type, operating range and screening option (if desired).



Valid Combinations					
Am2965 Am2966	PC DC, DCB, DM, DMB FM, FMB LC, LM, LMB XC, XM				

Valid Combinations

Consult the AMD sales office in your area to determine if a device is currently available in the combination you wish.



*Address and RAS/CAS drivers each drive 22 RAM inputs at each output. Timing skew is minimized by using one device for address lines and one device for RAS/CAS, spreading the CAS loading over four drivers to equalize the capacitive load on each driver.

DYNAMIC MEMORY CONTROL WITH ERROR DETECTION AND CORRECTION

ABSOLUTE MAXIMUM RATINGS

Storage Temperature65°C to +150°C Temperature (Ambient)
Under Bias55°C to +125°C
Supply Voltage to Ground Potential
Continous0.5V to +7.0V
DC Voltage Applied to Outputs For
High Output State0.5V to V _{CC} Max
DC Input Voltage0.5V to +7.0V
DC Output Current, Into Outputs200mA
DC Input Current30mA to +5.0mA

Stresses above those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to absolute maximum ratings for extended periods may affect device reliability.

OPERATING RANGES

Commercial (C) Devices	
Temperature	0°C to +70°C
Supply Voltage	+ 4.75V to + 5.25V
Military (M) Devices	
Temperature	55°C to +125°C
Supply Voltage	+4.5V to +5.5V
Operating ranges define those limits	over which the function-
ality of the device is guaranteed.	

DC CHARACTERISTICS over operating range unless otherwise specified

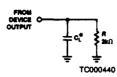
Parameters	Descriptions		Test Conditions (Note 1)		Min	Typ (Note 2)	Max	Units
V _{OH}	Output HIGH Volta	ige	V _{CC} = MIN V _{IN} = V _{IH} or V _{IL}	I _{OH} = -1mA	V _{CC} -1.15	V _{CC} -0.7V		Volts
M	Outrook LOW Make		V _{CC} = MIN	I _{OL} = 1mA			0.5	Volts
VOL	Output LOW Volta	ge	VIN = VIH or VIL	I _{OL} = 12mA			0.8	
VIH	Input HIGH Level		Guaranteed input logical HIGH voltage for all inputs		2.0			Volts
VIL			Guaranteed input logical LOW voltage for all inputs				0.8	Volts
Vį	Input Clamp Voltage		VCC = MIN, IIN = -18m	1A	1		-1.2	Volts
				DATA			-200	
IĮĽ	Input LOW Curren	t	V _{CC} = MAX, V _{IN} = 0.4V	TG, 2G			-400	μΑ
Iн	Input HIGH Current		V _{CC} = MAX, V _{IN} = 2.7V		1		20	μΑ
f)	Input HIGH Current Vo		V _{CC} = MAX, V _{IN} = 7.0V				0.1	mA
lozh	Off-State Current V _O = 2.7V		V _O = 2.7V				100	μΑ
[‡] OZL	Off-State Current V _O = 0.4V			1		-200	μA	
lor	Output Sink Curre	nt	t V _{OL} = 2.0V		50	·		mA
ЮН	Output Source Cu	rrent	V _{OH} = 2.0V	V _{OH} = 2.0V				mA
Isc	Output Short Circuit Current (Note 3)		V _{CC} = MAX		-60 (see I _{OH}		-200	mA
lcc	Supply Current .		All Outputs HIGH	V _{CC} = MAX Outputs Open		24	50	
		Am2965	All Outputs LOW			86	125]
			All Outputs Hi-Z			86	125	mA.
		All Outp	All Outputs HIGH			53	75	
		Am2966	All Outputs LOW	V _{CC} = MAX		92	130	1
			All Outputs Hi-Z			116	150	1

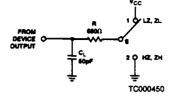
Notes: 1. For conditions shown as MIN or MAX, use the appropriate value specified under Operating Range for the applicable device type.

2. Typical limits are at V_{CC} = 5.0V, 25°C ambient and maximum loading.

3. Not more than one output should be shorted at a time. Duration of the short circuit test should not exceed one second.

SWITCHING TEST CIRCUIT



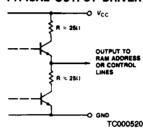


*tpd specified at C = 50 and 500pF.

Figure 1. Capacitive Load Switching.

Figure 2. Three-State Enable/Disable.

TYPICAL OUTPUT DRIVER



SWITCHING CHARACTERISTICS (TA = +25°C, VCC = 5.0V)

Parameters	Description	Test Condit	Test Conditions		Тур	Max	Units
			C _L = 0pF		6	(Note 4)	
t _{PLH}	Propagation Delay Time from LOW-to-HIGH Output	1	C _L = 50pF	6	9	15	ns
EOW-IO-Mari Output	Figure 1 Test Circuit	C _L = 500pF	18	22	30		
		Figure 3 Voltage Levels and Waveforms	C _L = 0pF		4	(Note 4)	ns
tPHL Propagation Delay Time HIGH-to-LOW Output	Propagation Delay Time from		C _L = 50pF	5	7	15	
	That Pio-Eon Cupat		C _L = 500pF	18	22	30	
†PLZ	Output Disable Time from	Figures 2 and 4, S = 1			11	50	
†PHZ	LOW, HIGH	Figures 2 and 4, S = 2			6.5	12	ns
^t PZL	Output Enable Time from	Figures 2 and 4, S = 1			12	20	
[†] РZH	LOW, HIGH Figures 2 and 4, S = 2				12	20	ns
^t SKEW	Output-to-Output Skew	Figures 1 and 3, C _L = 50pF			±0.5	±3.0 (Note 5)	ns
VONP	Output Voltage Undershoot	Figures 1 and 3, C _L = 50pF			0	-0.5	Volts

SWITCHING CHARACTERISTICS over operating range unless otherwise specified (Note 6)

				COMMERCIAL		MILITARY		
Parameters	Description	Test Conditions		Min	Max	Min	Max	Units
	Propagation Delay Time		C _L = 50pF	4	17	4	20	ns
	LOW-to-HIGH Output	Figures 1 and 3	C _L = 500pF	18	35	18	40	
. Propagation Delay Time		C _L = 50pF	4	17	4	20		
TPHL .	tPHL HIGH-to-LOW Output	Figures 1 and 3	C _L = 500pF	18	35	18	40	ns
telz	Output Disable Time from	Simusa O and 4	S = 1		24		24	ns
^t PHZ	LOW, HIGH	Figures 2 and 4	S = 2		16		16	
tpzL	Output Enable Time from	Figures 2 and 4	S = 1		28		28	ns
tрzн	LOW, HIGH	rigures 2 and 4	S = 2		28		28	
VONP	Output Voltage Undershoot	Figures 1 and 3, C	Figures 1 and 3, CL = 50pF		-0.5		-0.5	Volts

Notes: 4. Typical time shown for reference only - not tested.

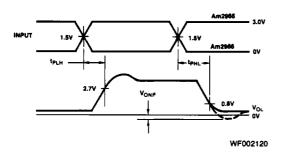
5. Time Skew specification is guaranteed by design but not tested.

6. AC performance over the operating temperature range is guaranteed by testing defined in Group A, Subgroup 9.

7. $T_C = -55$ to +125°C for Flatpak versions.

TYPICAL SWITCHING CHARACTERISTICS

VOLTAGE WAVEFORMS



 $t_f = t_f = 2.5 \text{ns}$ f = 2.5 MHz $t_{DW} = 200 \text{ns}$

Figure 3. Output Drive Levels.

The RAM Driver symmetrical output design offers significant improvement over a standard Schottky output by providing a balanced drive output impedance (*25 Ω both HIGH and LOW), and by pulling up to MOS VOH levels (VCC – 1.5V). External resistors, not required with the RAM Driver, protect standard Schottky drivers from error causing undershoot but also slow the output rise by adding to the internal R.

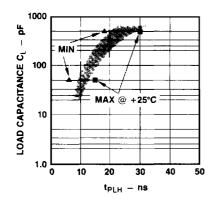
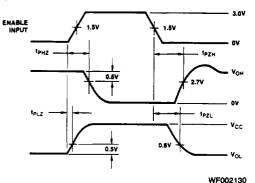


Figure 5. t_{PLH} for $V_{OH} = 2.7$ Vol vs. C_L .



 $t_{\Gamma} = t_{f} = 2.5 \text{ns}$ f = 1 MHz $t_{DW} = 800 \text{ns}$

Figure 4. Three-State Control Levels.

The RAM Driver is optimized to drive LOW at maximum speed based on safe undershoot control and to drive HIGH with a symmetrical speed characteristic. This is an optimum approach, because the dominant RAM loading characteristic is input capacitance.

The curves shown below provide performance characteristics typical of both the inverting (Am2965) and non-inverting (Am2966) RAM Drivers.

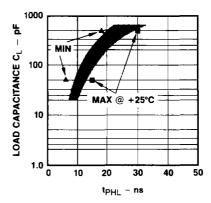


Figure 6. tpHL for Vol = 0.8 Volts vs. CL.

The curves above depict the typical tPLH and tPHL for the RAM Driver outputs as a function of load capacitance. The minimums and maximums are shown for worst case design. The typical band is provided as a guide for intermediate capacitive loads.